

1.Emitter 2.Collector 3.Base

NPN Triple Diffused Planar Silicon Transistor

Symbol	Parameter	Value	Units
V _{CBO}	Collector-Base Voltage	700	V
/ _{CEO}	Collector-Emitter Voltage	400	V
√ _{EBO}	Emitter-Base Voltage	12	V
с	Collector Current (DC)	4	Α
CP	* Collector Current (Pulse)	8	A
В	Base Current (DC)	2	Α
BP	* Base Current (Pulse)	4	Α
°c	Collector Dissipation (T _C =25°C)	30	W
Г _{STG}	Storage Temperature	- 65 ~ 150	°C

Absolute Maximum Ratings T_C=25°C unless otherwise noted

= 5ms, Duty Cycle ≥ 1.0%

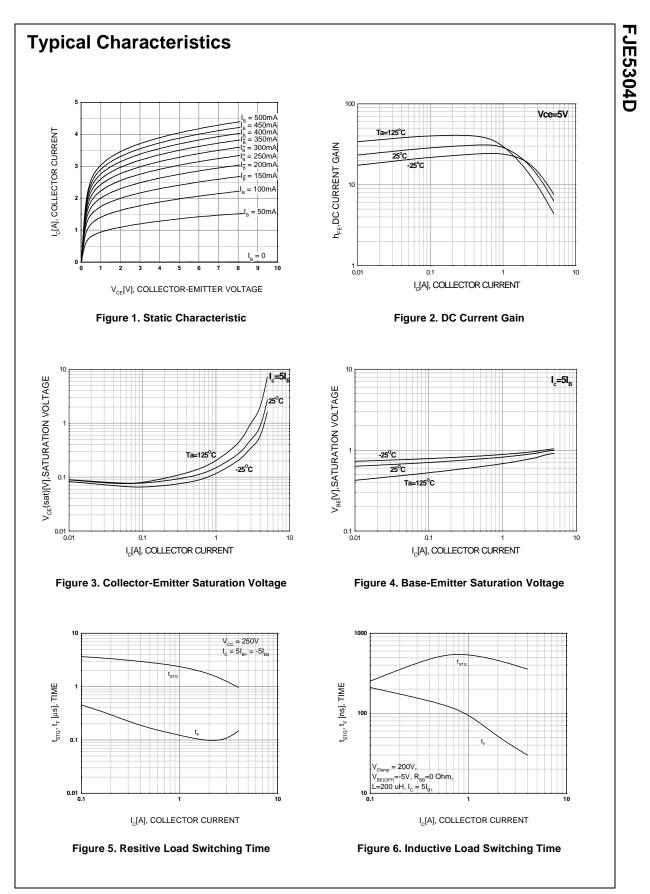
Electrical Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
BV _{CBO}	Collector-Base Breakdown Voltage	$I_{\rm C} = 1$ mA, $I_{\rm E} = 0$	700			V
BV _{CEO}	Collector-Emitter Breakdown Voltage	$I_{\rm C} = 5 {\rm mA}, I_{\rm B} = 0$	400			V
BV _{EBO}	Emitter-Base Breakdown Voltage	$I_{\rm E} = 1$ mA, $I_{\rm C} = 0$	12			V
I _{CES}	Collector Cut-off Current	V _{CE} = 700V, V _{EB} = 0			100	mA
I _{CEO}	Collector Cut-off Current	V _{CE} = 400V, IB = 0			250	mA
I _{EBO}	Emitter Cut-off Current	$V_{EB} = 12V, I_{C} = 0$			100	mA
h _{FE}	DC Current Gain	$V_{CE} = 5V, I_C = 10mA$ $V_{CE} = 5V, I_C = 2A$	10 8		40	
V _{CE} (sat)	Collector-Emitter Saturation Voltage	$I_{C} = 0.5A, I_{B} = 0.1A$ $I_{C} = 1A, I_{B} = 0.2A$ $I_{C} = 2.5A, I_{B} = 0.5A$			0.7 1.0 1.5	V
V _{BE} (sat)	Base-Emitter Saturation Voltage	$I_{C} = 0.5A, I_{B} = 0.1A$ $I_{C} = 1A, I_{B} = 0.2A$ $I_{C} = 2.5A, I_{B} = 0.5A$			1.1 1.2 1.3	V
V _f	Internal Diode Forward Voltage Drop	I _F = 2A			2.5	V

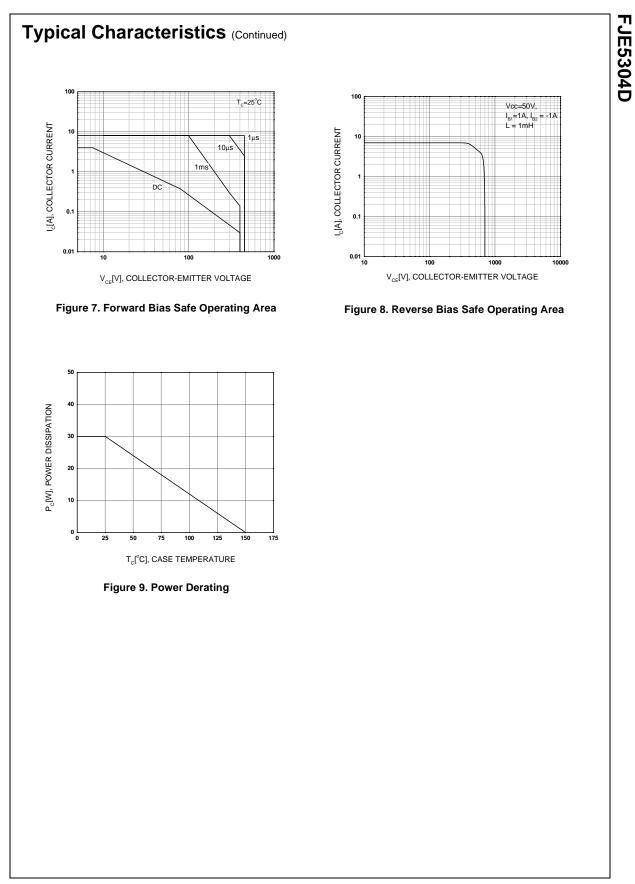
Symbol	Parameter	Test Condition	Min.	TYP.	Max.	Units
Inductive Lo	bad Switching (V _{CC} = 200V)	·	•	•	•	•
t _{stg}	Storage Time	$I_{\rm C} = 2A, I_{\rm B1} = 0.4A$		0.6		μs
f	Fall Time	$V_{BE}(off) = -5V,$ L = 200µH		0.1]
Resistive Lo	oad Switching (V _{CC} = 250V)	·	•		•	
t _{stg}	Storage Time	$I_{\rm C} = 2$ A, $I_{\rm B1} = I_{\rm B2} = 0.4$ A			2.9	μs
tf	Fall Time	T _P = 30μs		0.2		

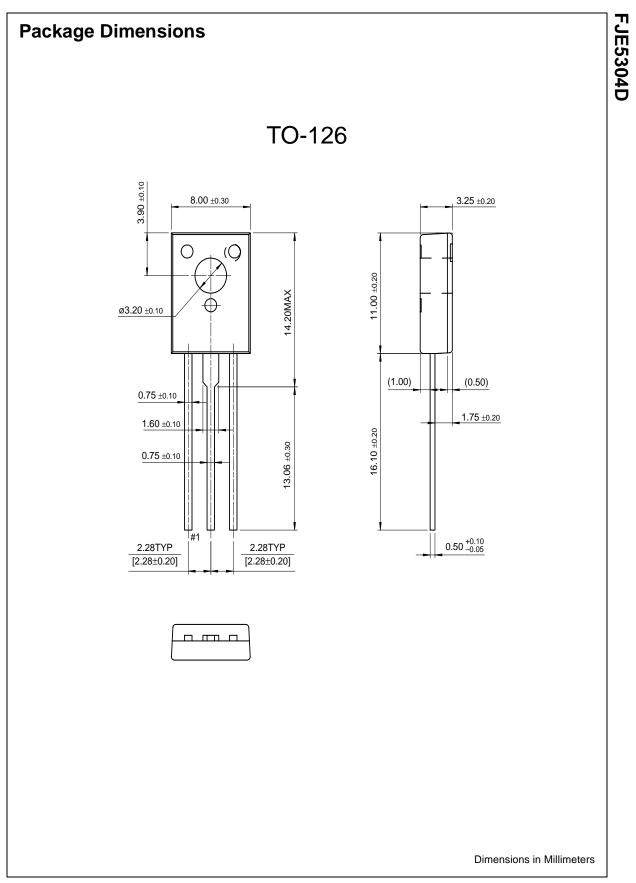
Thermal Characteristics $T_{C} = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	4.17	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient	83.3	°C/W



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